

UCC28782 System Bring Up Guideline and Common Issues



ABSTRACT

This application note presents a step-by-step debug process to help designers debug their UCC28782 high-frequency active clamp flyback (ACF) converters in an efficient manner. Firstly, VDD start and typical system operation waveforms are presented, then the frequently happen protections waveforms are demonstrated, finally common issues and solutions are shown. Assume the reader has read the UCC28782 data sheet in detail and has some basic knowledge of ACF topology before reading this application note. Together, with another application note [Debugging UCC28780 ACF Converter Start-up Issues](#), we can start the ACF journey.

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1 Initial Board Visual Inspection and Start-up Check

Before powering up the design board, the first step is to thoroughly review the design to make sure all design parameters are calculated properly. The [Excel Design Calculator](#) is a helpful tools to check the accuracy of the design. It is recommended to do a visual inspection to check for the following:

- Solder bridges
- Solder balls
- Solder skips
- Cold solder joints
- Lifted pads

After visual inspection, the user can also use a multimeter to check the solder, Multimeter locked to *diode* location, Red probe connected to IC ground, Black probe connected to each pin. There should be a ~0.5 V-0.7 V voltage presents on the multimeter, if not, check solder of this pin. [Figure 1-1](#) demonstrates probing UCC28782 Pins with a digital multimeter.



Figure 1-1. Probing UCC28782 Pins with a Digital Multimeter

When the solder inspection is complete, the board can input a low voltage, next steps are input short-circuit investigation / HV start circuits operation check / CS pin fault detection and input brown in voltage (startup voltage) detection:

1. Step 1: Set input voltage source to $V_{in}=5$ Vrms while limiting its current to 0.5 A, measure the input current. After a brief low inrush peak current, there should be almost zero continuous input current, if an excessive current is observed, there may be a short or abnormally low impedance in the circuit.
2. Step 2: If zero current is observed. Move to VDD pin to check if HV start circuits working properly, 25 Vrms voltage implied on the input, the captured waveform of VDD as shown in [Figure 1-2](#): If VDD voltage can be charged to ~17.5 V, it indicates the HV start circuits working normal. if not please refer to [Debugging UCC28780 ACF Converter Start-up Issues](#) section 7.3, *Start-up Failure Due to VDD Clamped Low*.

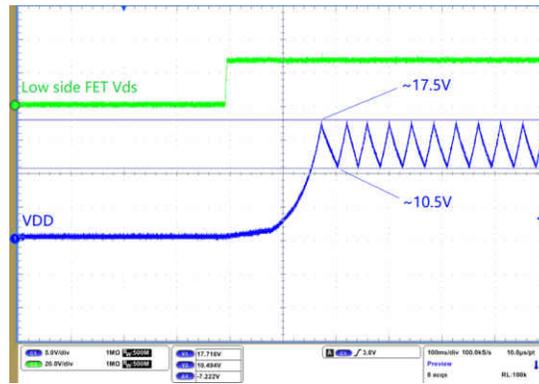


Figure 1-2. VDD Start Up and Hiccup at Below Brown In Voltage

- Step 3: Zoom in waveform at the point when VDD reaches to its turn on threshold (17.5 V), capture low side driver signal PWML, if only one pulse with a width of 2us is observed, see [Figure 1-4](#), this is the correct behavior at the input voltage which lower than start up voltage. Please refer to [Debugging UCC28780 ACF Converter Start-up Issues](#) section 6.1 *Observation of Zero or Only One PWML Pulse*.

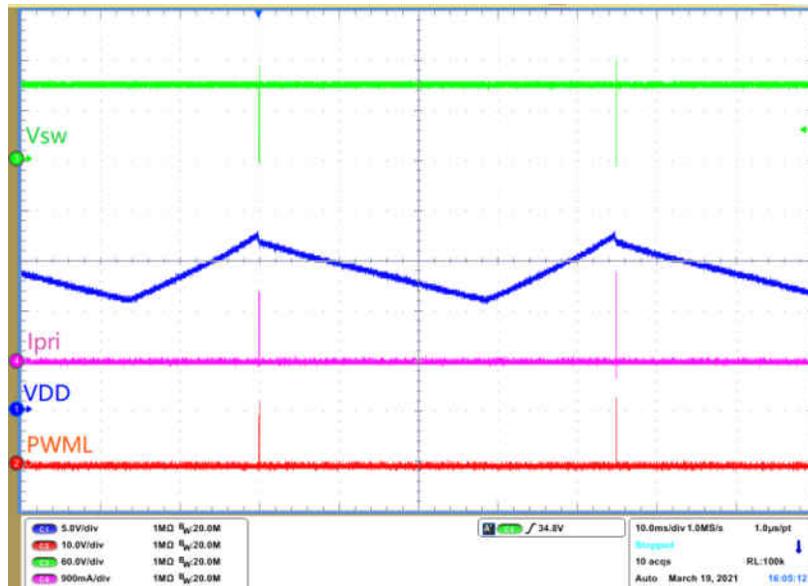


Figure 1-3. VDD Restart

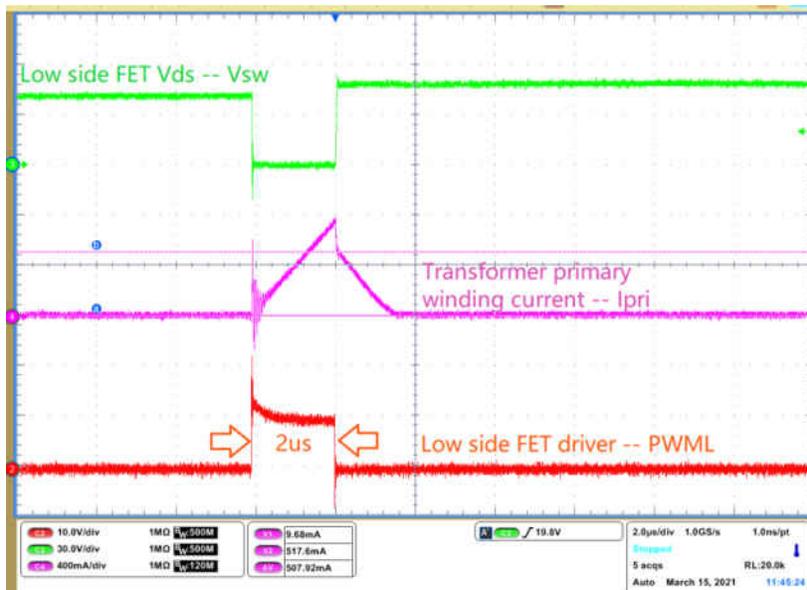


Figure 1-4. CS Pin Fault Detection - Only 1 Pulse With 2µs Width

- Step 4: Gradually increase input voltage until the user can see four consecutive pulses shown in Figure 1-5. The first pulse is for CS pin fault detection, the second, third, fourth pulses are for brown in voltage detection. When the AC input voltage is lower than brown in voltage. The user will always see four pulses at each VDD restart cycle. Further increasing the input voltage until it is above the brown in voltage, the board should be powered up if there is no protection occurring.

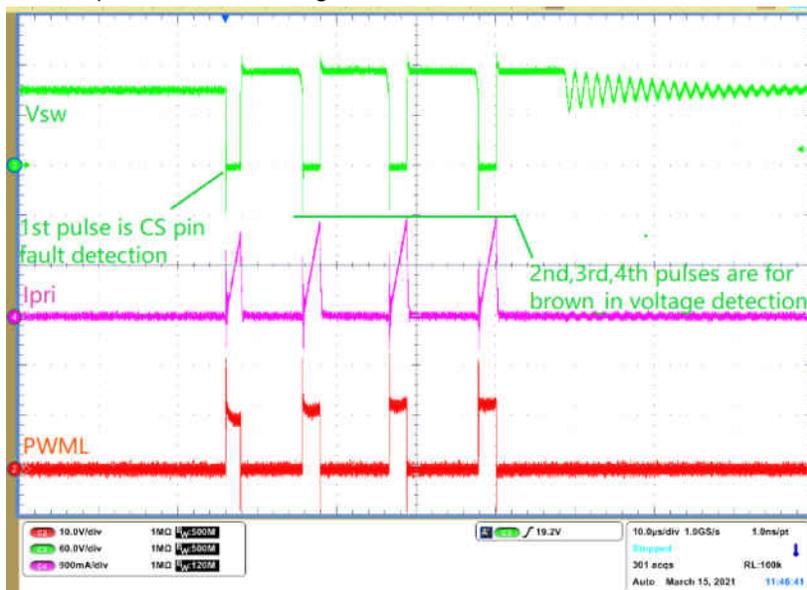


Figure 1-5. Brown-in Voltage Detection – 4 Consecutive Pulses

2 Typical System Operating Waveforms

UCC28782 contains six modes of operation that summarized in [UCC28782 data sheet](#) Table 8-1. From no load to full load, the operation modes include Survival Mode, SBP2(Second StandBy Power Mode), SBP1, (First StandBy Power Mode) LPM (Low Power Mode), ABM (Adaptive Burst Mode), AAM (Adaptive Amplitude Modulation), The survival mode only kicks in when VDD voltage lower than the 13-V survival mode threshold and also performs the clamping capacitor balancing function to reduce the voltage stress of the secondary side rectifier. Typically, the system does not enter survival mode during regular load change, such as smooth load increase and decrease. The survival mode might kick in at a large output load remove, overshoot on output results in controller stop switching in a long time, then the VDD voltage might drop to touch the 13-V survival mode threshold. The following waveforms show each mode operation (no load to full load).

2.1 SBP2 Mode

At no load or very light load, PWMH is disabled and there are four PWML pulses in each burst packet. The peak current of each pulse is programmable through the resistance from IPC pin to ground. See [Figure 2-1](#).

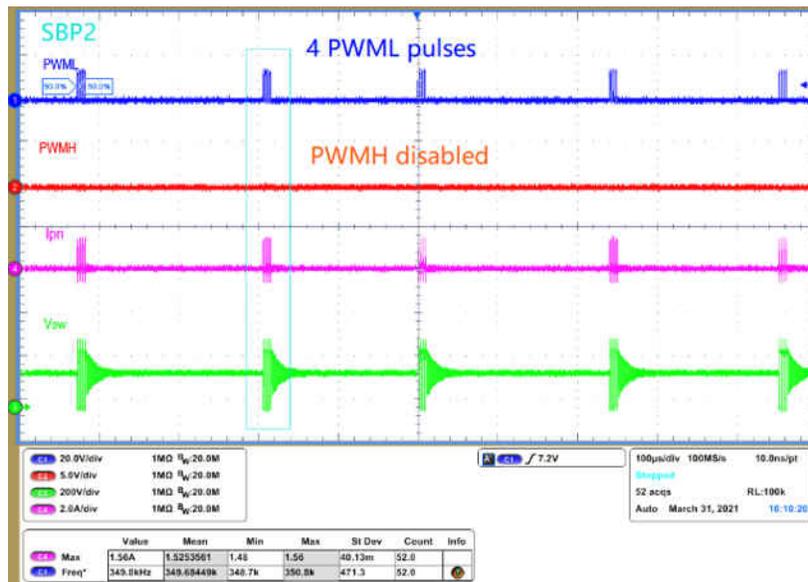


Figure 2-1. SBP2 Mode Operation Waveform

2.2 SBP1 Mode

Gradually increase load at SBP2 mode, the system will entry SBP1 mode, PWMH is still disabled and there are two PWML pulses in each burst packet. The peak current is fixed and this is determined by $V_{CST(MIN)}$. Burst frequency is less than 25 khz and it is variable based on the load. As shown in [Figure 2-2](#).

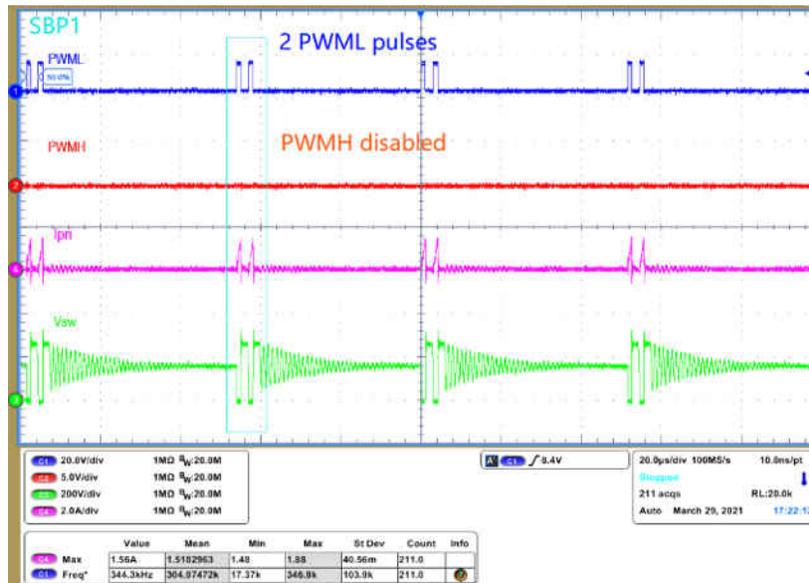


Figure 2-2. SBP1 Mode Operation Waveform

2.3 LPM mode

Gradually increase load at SBP1 mode, the system will enter LPM mode, PWMH is disabled and there are two PWML pulses in each burst packet. But, the peak current is variable, as V_{CST} will vary from $V_{CST(MIN)}$ to $V_{CST(BUR)}$. The burst frequency is fixed at 25 kHz. See Figure 2-3.

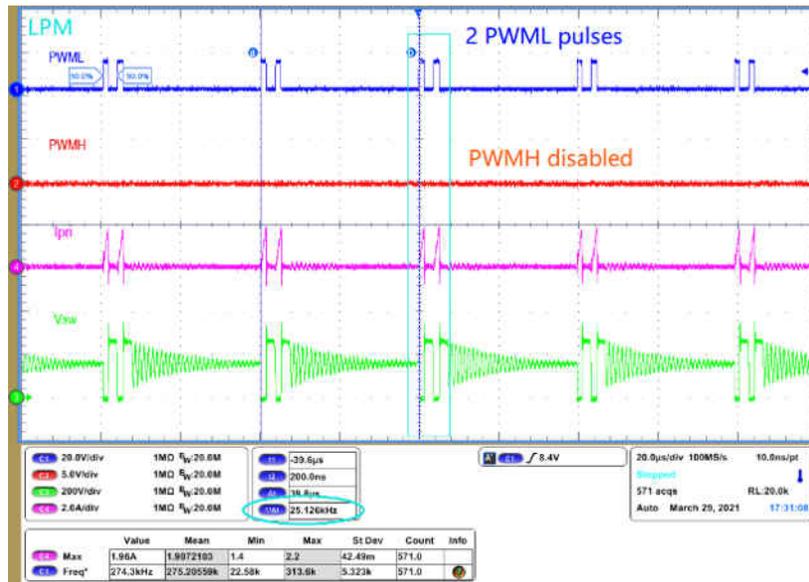


Figure 2-3. LPM Mode Operation Waveform

2.4 LPM to ABM Mode Transition

As load increases, V_{CST} reaches $V_{CST(BUR)}$, LPM mode transient to ABM, PWMH is enabled at ABM. A large negative current for example, balancing current can be observed when the first PWMH is enabled as shown in Figure 2-4.

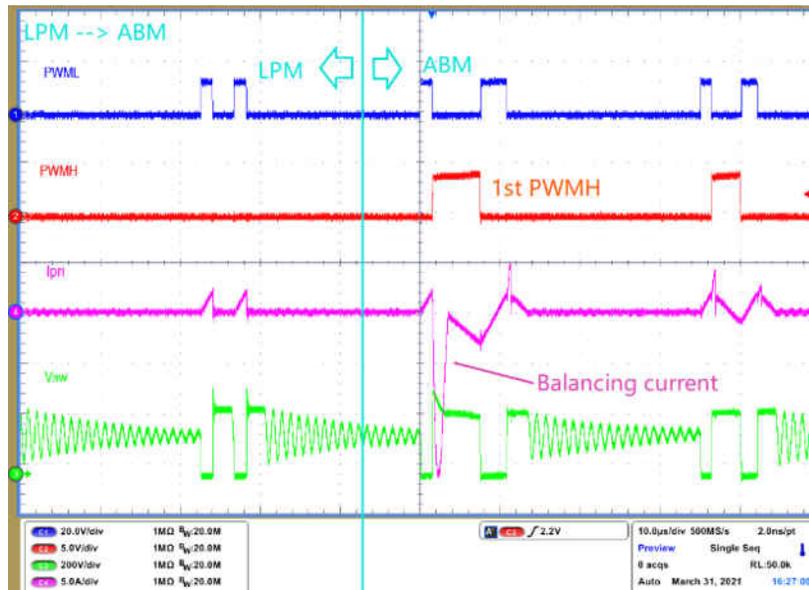


Figure 2-4. LPM to ABM Mode Transition

2.5 ABM Mode

At ABM mode, the peak current is clamped at $V_{CST(BUR)}/R_{cs}$, PWMH is enabled, so Zero-Voltage Switching (ZVS) is achieved except for the first switching cycle. The number of PWML pulses (N_{SW}) is modulated to ensure burst frequency stays above 25kHz. As load increases, burst frequency becomes higher and reaches to the high-level burst frequency threshold $f_{BUR(UP)}$, the ABM loop commands N_{SW} to be increased by one pulse to push burst frequency f_{BUR} below $f_{BUR(UP)}$. Additional details can be found in [UCC28782 data sheet](#) section 8.4.6.

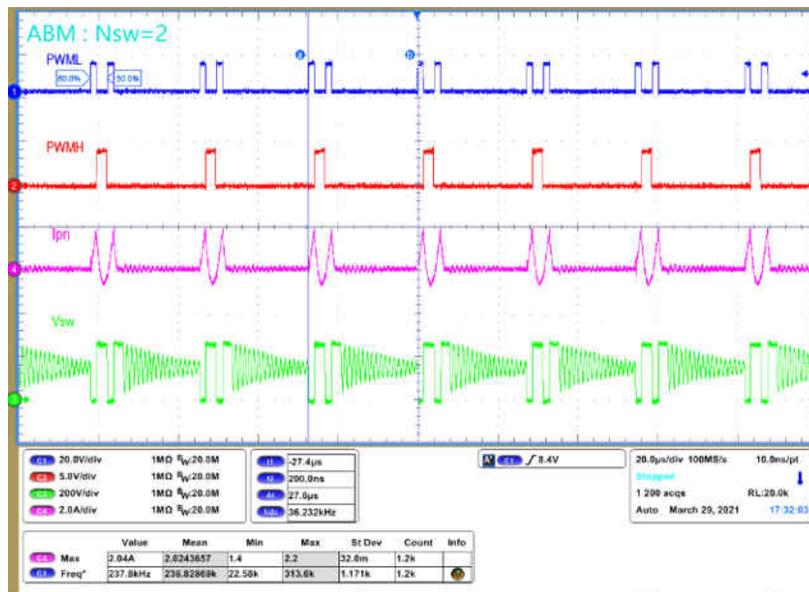


Figure 2-5. ABM Mode PWML Pulse $N_{SW}=2$

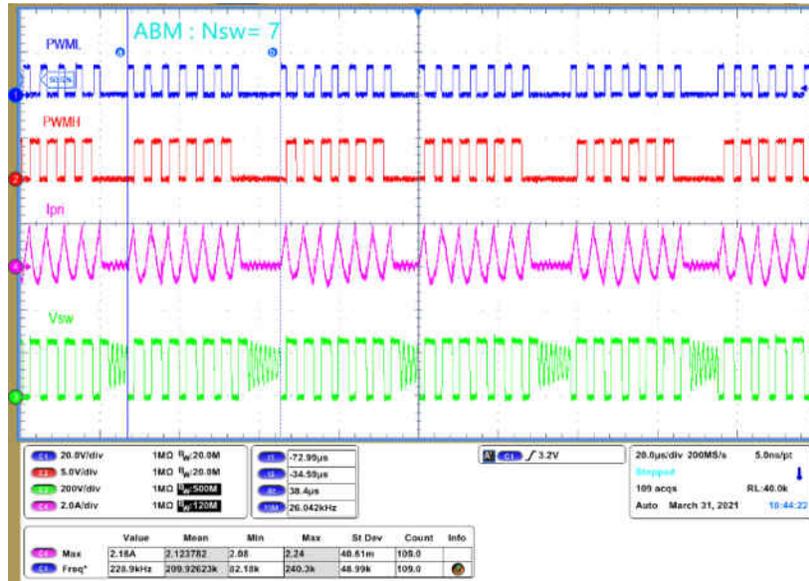


Figure 2-6. ABM Mode PWM Pulse $N_{sw}=7$

2.6 ABM to AAM Mode Transition

Figure 2-7 demonstrates ABM transition to AAM. As load is closed to the boundary of ABM and AAM, the two adjacent burst packets with the maximum pulse count can start to bundle together. To mitigate the output ripple and audible noise concerns, when the bundled burst packet appears two times with eight sequential burst cycles, the controller will reduce V_{BUR} . The less energy per cycle with a lower V_{BUR} will force the control loop to transition from ABM to AAM smoothly.

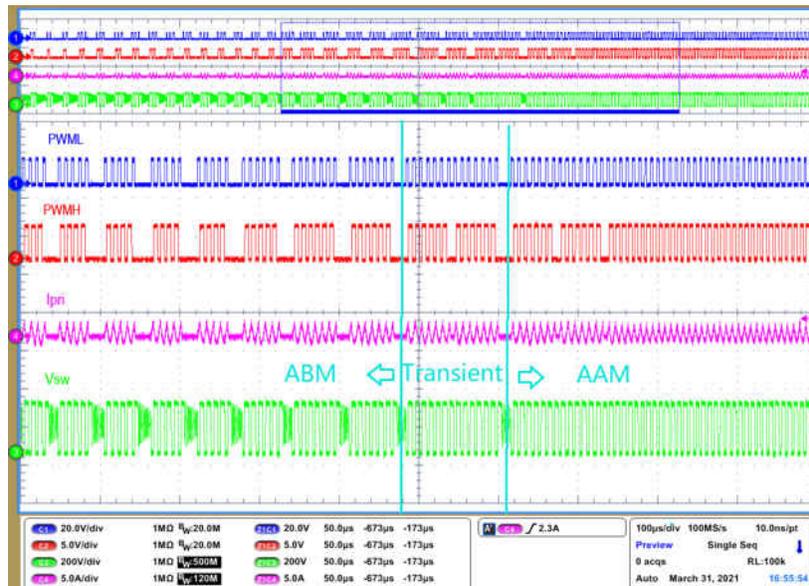


Figure 2-7. ABM to AAM Mode Transition

2.7 AAM Mode

At AAM mode Figure 2-8, PWML and PWMH alternate turn on in a complementary fashion with dead-time in between, as load current increases Figure 2-9, peak current increases while the switching frequency decreases.

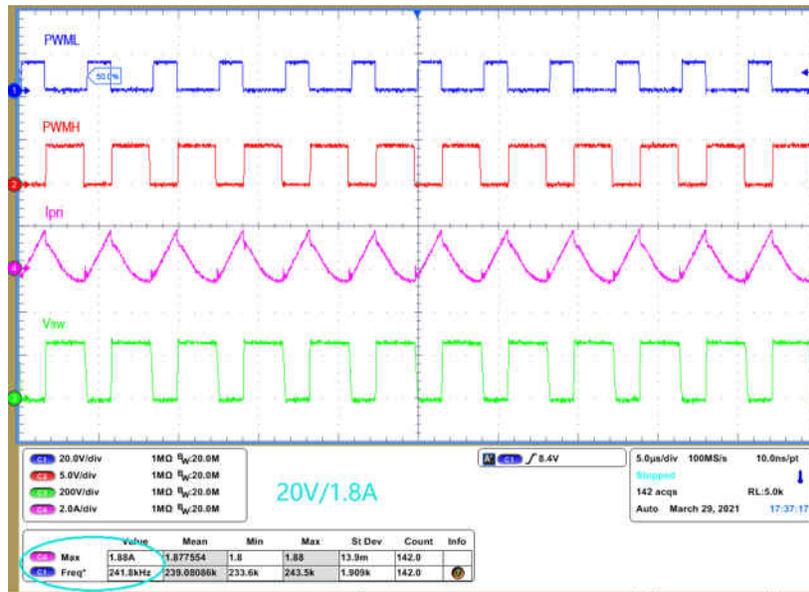


Figure 2-8. AAM Mode Medium Load

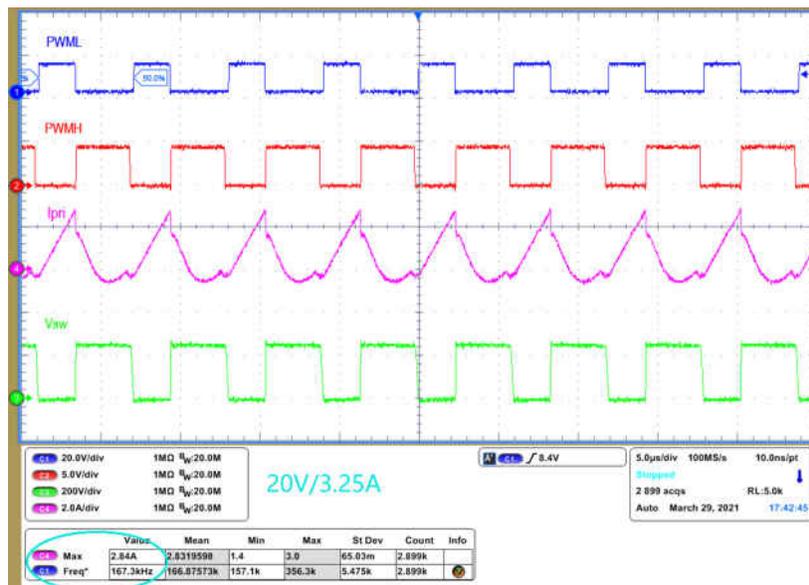


Figure 2-9. AAM Mode Heavy Load

3 Typical System Protection Waveforms

The UCC28782 provides extensive protections on different system fault scenarios for robust operation. All system protection features are summarized in [UCC28782 data sheet Table 8-3](#), and the pin fault protections are summarized in the data sheet Table 8-4. If the input voltage is higher than brown_in voltage, but output voltage cannot be regulated, there is a high chance that some protections might be triggered, this section describes some typical system protections.

3.1 Over-Power Protection (OPP)

The two key things used to identify what protection happens on the board are *delay to action* and *action*, which also listed in UCC28782 data sheet Table 8-3, for OPP, *delay to action* shown in [Figure 3-1](#) is $V_{CST} \geq V_{CST(opp)}$ and maintain above 160ms, *action* shown in [Figure 3-2](#) is t_{FDR} restart(1.5s).

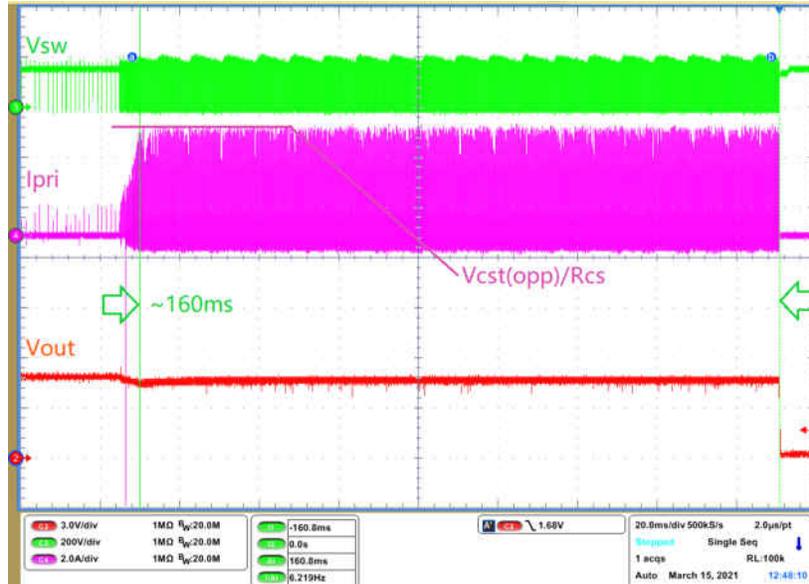


Figure 3-1. OPP Delay to Action

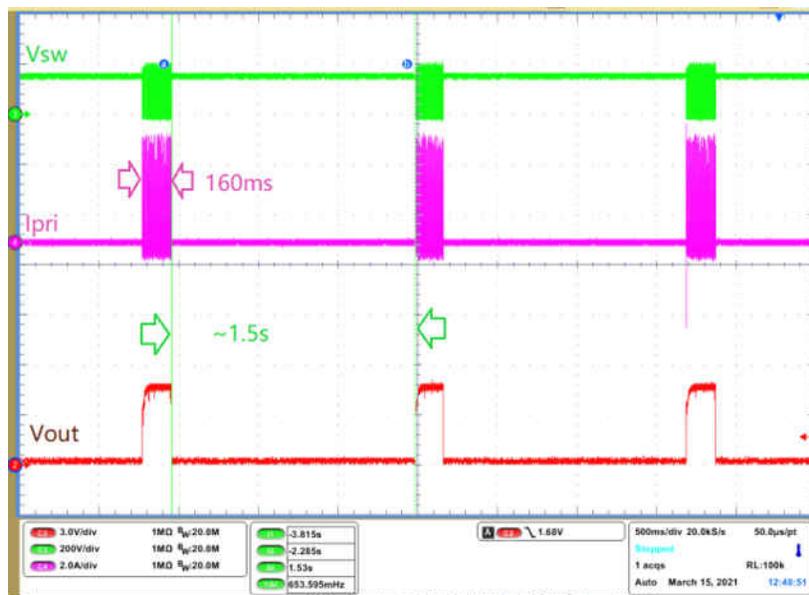


Figure 3-2. OPP Action

CH3: Low side FET Vds (Vsw), CH4: Transformer primary winding current (Ipri), CH2: Output voltage (Vout).

3.2 Output Overvoltage Protection (OVP)

Output voltage is detected by controller through VS pin, However, it is not recommended to probe VS pin directly as the noise introduced by probing could cause protection mis-triggering. Instead, AUX winding voltage can be used for identifying whether OVP happens. If the divided voltage on VS pin exceed OVP threshold for three consecutive pulses, OVP is triggered.

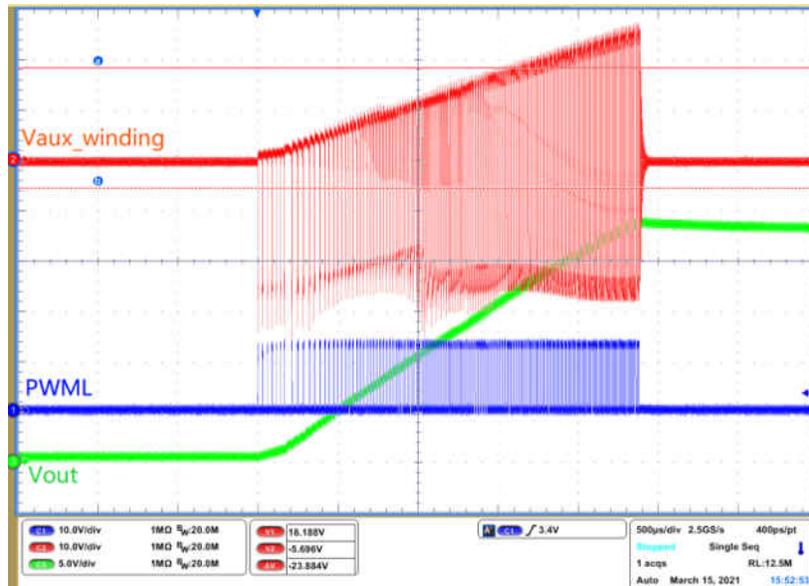


Figure 3-3. OVP Delay to Action

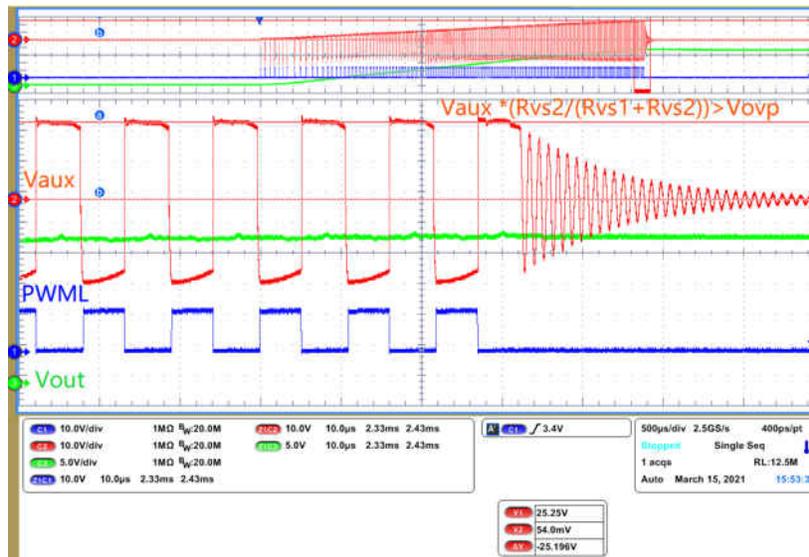


Figure 3-4. OVP Delay to Action (Zoom In)

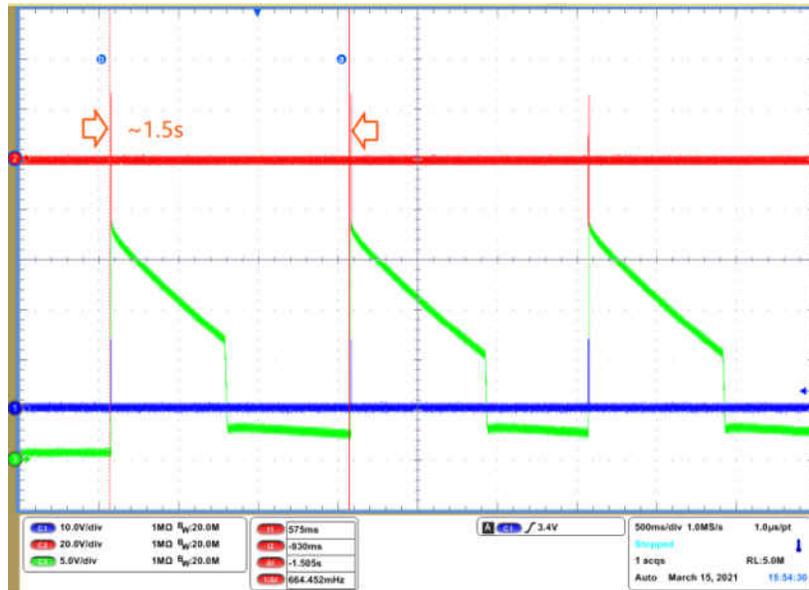


Figure 3-5. OVP Action

CH2: AUX winding voltage (V_{aux}), CH1: PWML, CH3: Output voltage.

3.3 Output Short-Circuit Protection (SCP)

For SCP, V_{DD} voltage needs to drop to $V_{DD(OFF)}$, the auxiliary winding voltage can reflect output voltage. If output been shorted, the AUX winding voltage during PWMH on time is also been clamped to a low voltage. Then UCC28782 internal current threshold (V_{CST}) can reflect the V_{VS} pin voltage at $V_{VS(SM2)}$. This can be reflected by capturing transformer primary winding current which equal to $V_{VS(SM2)}$ divide current sense resistor R_{cs} . CH4 in Figure 3-6 shows V_{VS} pin is at $V_{VS(SM2)}$ stage.

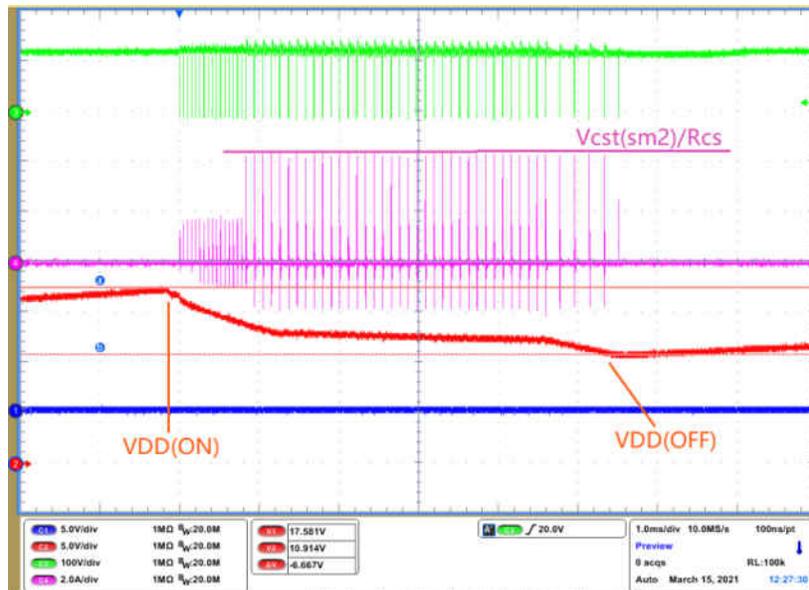


Figure 3-6. SCP Delay to Action

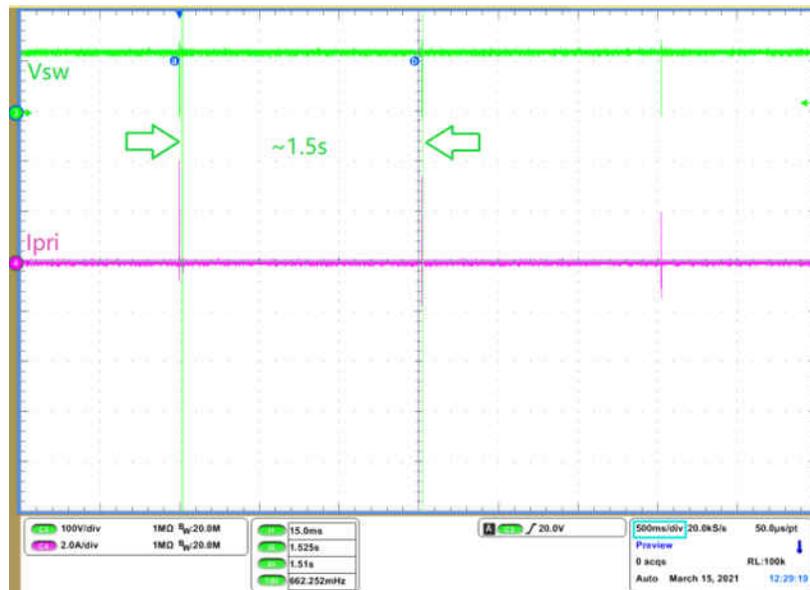


Figure 3-7. SCP Action

CH3: Low side FET Vds, CH4: Primary current, CH2: VDD

Additional protections details and corresponding solutions can be found in [Debugging UCC28780 ACF Converter Start-up Issues](#). application note.

4 Common Issues and Solutions

This section covers some common issues that a designer might face during the board debug stage and corresponding solutions are presented. The following three subsections covers regulation, light load, and transient conditions.

4.1 VDD Boost Converter Survival Mode

4.1.1 Survival Mode Due To Boost Inductor DCR Too High.

UCC28782 integrates a boost converter to supply VDD in a wide output voltage range application, such as USB PD charger. The typical UVLO threshold of boost converter is 1.23 V, If BIN capacitors are occasionally completely discharged, shown in Figure 4-1, resulting in additional power losses, irregular operation and higher output ripple, this could be caused by boost inductor DCR too high which results in V_{BIN} UVLO not proper been detected (UVLO off threshold of V_{BIN} is around 1.23V, large DCR of boost inductor will lead to V_{BIN} always higher than 1.23 V during boost Mosfet turn on time.). The boost converter always turns on until the energy on BIN capacitors be consumed up.

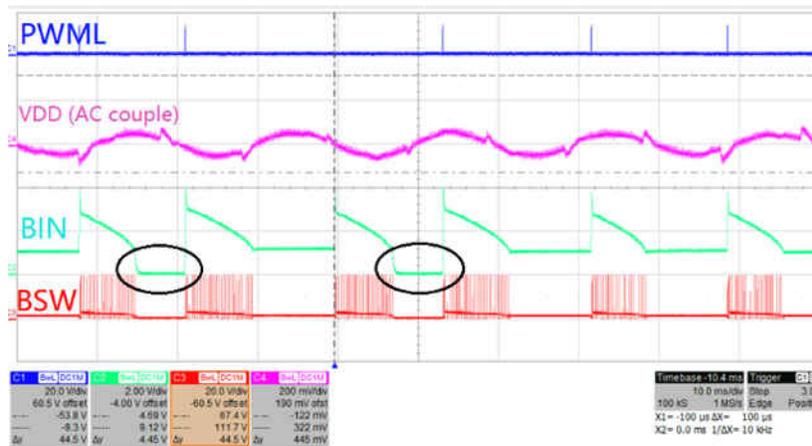


Figure 4-1. Boost Inductor DCR > 1 ohm

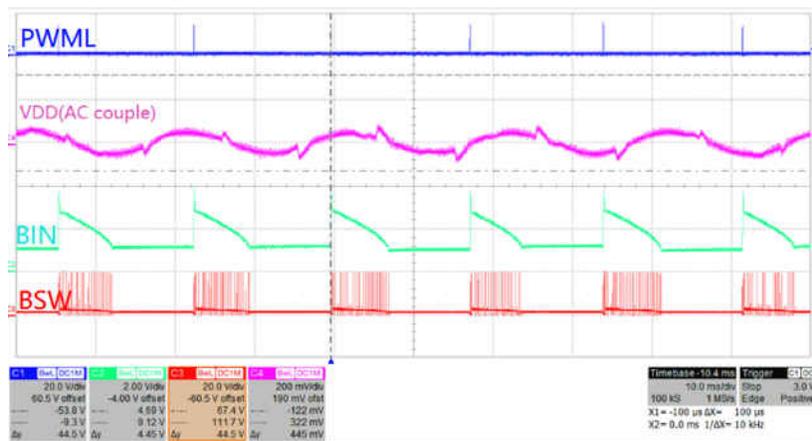


Figure 4-2. Boost Inductor DCR = 0.56 ohm

Solution: Choose the boost inductor with DCR less than 1 ohm. 0.5 ohm ~0.7 ohm is preferred.

4.1.2 System Stays In Survival Mode When the Output Voltage is Low Such as 3.3V/5V/9V

If this occurs, it might be due to BIN and VDD capacitance are too small. At no load, energy in each survival mode pulse is intended to go to BIN and VDD networks on the primary side of transformer. If the auxiliary winding resistance R_{AUX} is high, it can be difficult to pass this energy to BIN capacitors, and most of the energy

goes to output instead. This results in more survival mode pulses than expected to get energy into BIN and VDD which overcharges Vout.

Solution: Use higher BIN and VDD capacitance to *attract* energy to AUX side. ~47 uF on BIN and ~22 uF on VDD is a good start.

Higher capacitors at BIN pin C_{BIN} keeps BIN voltage lower than reflected Vout so pulse current steers to BIN instead of Vout. Higher C_{VDD} keeps VDD higher so fewer survival mode pulses are required. Low R_{AUX} allows survival mode pulse energy to steer easily in to lower-value BIN cap.

4.2 10% Load Efficiency Might not Meet spec. in USB-PD Application, Especially at 5 V/9 V Output Condition

The result could be caused by improper current sense resistor R_{cs} setting and not using the IPC pin resistor. This process results in a higher burst switching frequency. At 10% load the switching losses become dominant, reduce switching frequency helps reduce switching losses and improve efficiency.

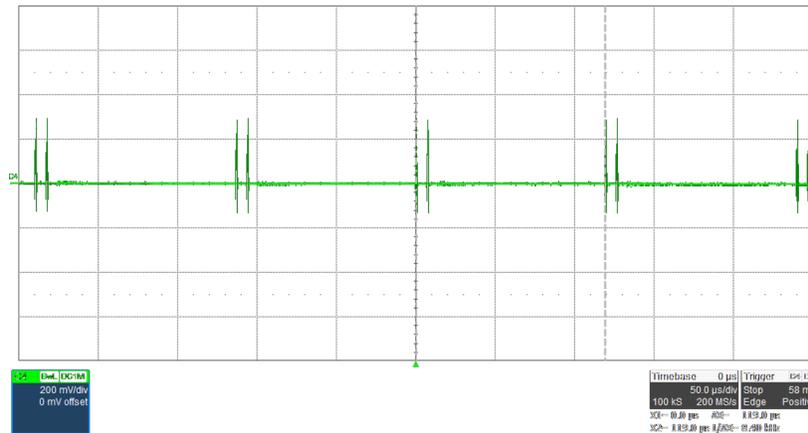


Figure 4-3. Operating at SBP1 Mode

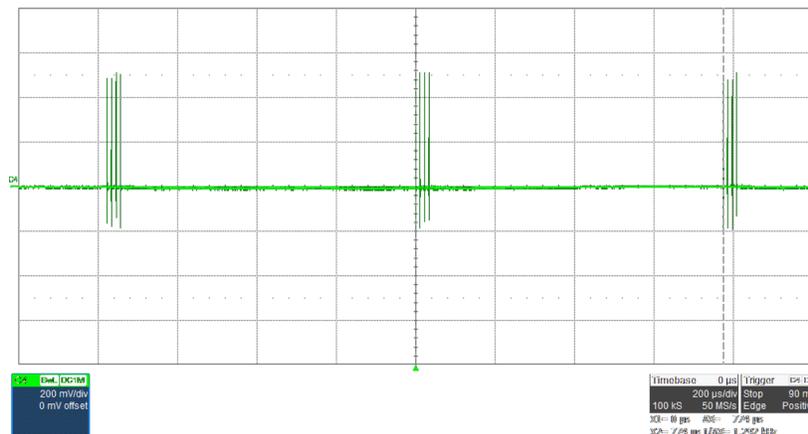


Figure 4-4. Operating at SBP2 Mode

Solution:

1. Reduce current resistor R_{cs} and increase CS pin filter capacitor C_{cs} to push operation mode from SBP1 into SBP2.

Figure 4-3 shows the waveform of SBP1 operation, Figure 4-4 shows the waveform after reducing R_{cs} or increase C_{cs} to push $F_{sw} < 8$ kHz. this helps the system operates at SBP2 mode and improve efficiency significantly.

2. Add a resistor between IPC and AGND

Disconnecting a resistor from IPC to AGND is not a mandatory requirement, but connecting a resistor in here helps for improving the light load efficiency especially when 5 V/9 V can't meet the average efficiency spec.

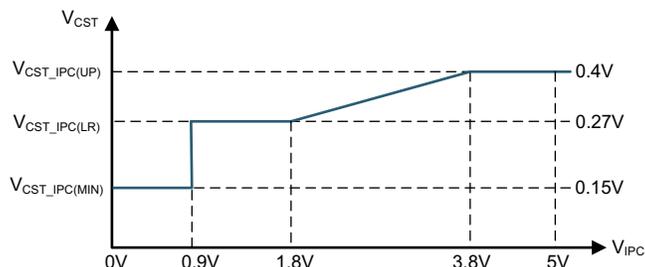


Figure 4-5. IPC Pin Resistor Setting

There is a 50 uA current source out of the IPC pin, the voltage on IPC pin resistor (V_{IPC}) can program the peak current threshold (V_{CST_IPC}) at SBP2 mode. Higher peak current can further reduce fsw then improve 10% load efficiency, but higher peak current may cause audible noise, trade off between efficiency and noise level maybe need to be made.

4.3 Transient

4.3.1 BIN/BSW Pin Damage During LPM to ABM Mode Transition

This transition could be caused by RDM or BUR pin resistor not selected properly. When the power stage running at LPM mode, high-side driver PWMH is disabled, transformer leakage energy will be accumulated at clamp capacitors while results in voltage on clamp capacitors slightly higher than output reflected voltage, as load increasing, power stage will transfer from LPM to ABM mode, there is a large balancing current between clamp capacitors and output capacitors when the first PWMH enabled, if PWMH on time is shorter than the resonance time of leakage inductance and clamp capacitors. NON-ZCS turn off will happen as shown in Figure 4-6, A sharp di/dt on leakage inductance causes high voltage spike which coupling to AUX winding, there is a potential risk that damage BIN/BSW pins, and SR FET also shows over voltage stress at this moment.

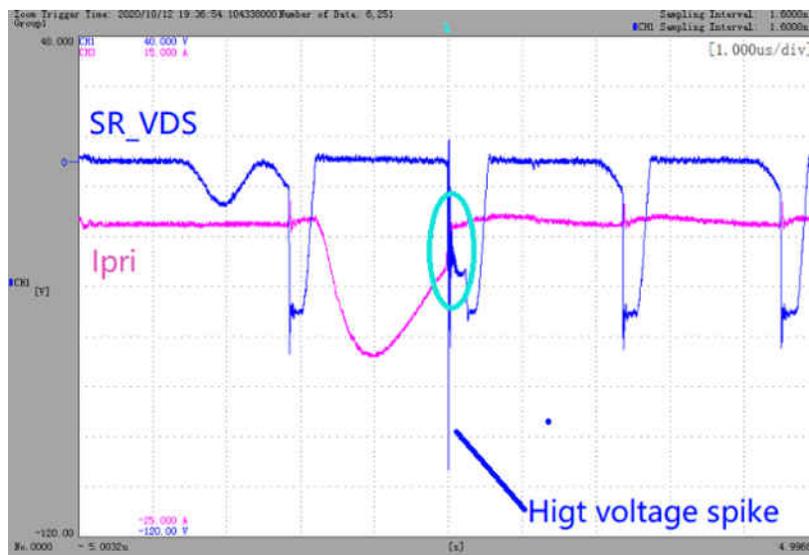


Figure 4-6. SR FET Non-ZCS Turn Off

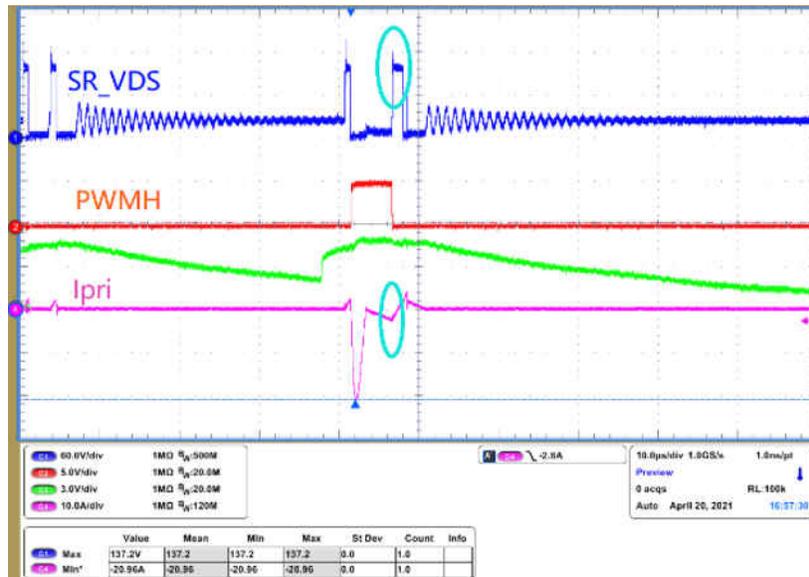


Figure 4-7. SR FET ZCS Turn Off

Solution:

1. Re-calculate RDM pin resistor value, The R_{RDM} calculation equation shown in [UCC28782 data sheet](#) equation (11). If the actual value on the tested board is close to calculated value, minor increase RDM resistor until the user can see NON-ZCS turn off disappear, see [Figure 4-7](#)
2. Decrease down-side resistor value of BUR pin divider. So the peak current at LPM is reduced, in this way, the energy stored in clamp capacitors is also reduced. This process will assist for smaller balancing current.

4.3.2 SR MOSFET VDS Overstress at Survival Mode

This process could rarely be observed at full load transient to no load, output voltage overshoot results in UCC28782 long time pulse stop, shown in [Figure 4-8](#). VDD drop to around 13-V due to the controller still consume the energy on VDD capacitances even pulse is stopped. While BIN capacitors been over discharged during this time. When survival mode kicks in, most of current flow into BIN pin caps, less current go to SR FET, SR turn on at minimum on time that a reverse current can be seen at it's turn off edge. This reverse current will trigger next turn on pulse that lead to SR turn on again and again.



Figure 4-8. SR Vds Overstress When Survival Mode Kick In

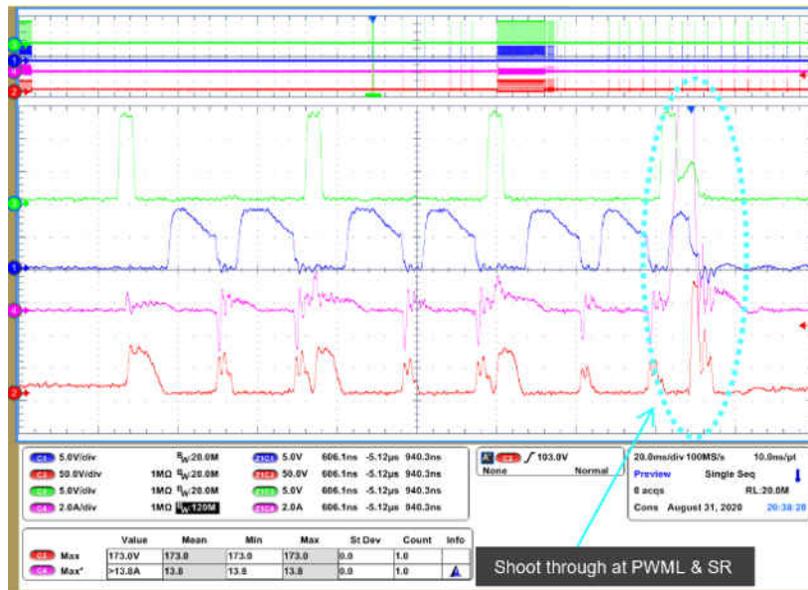


Figure 4-9. SR Vds Overstress – Zoom In

When PWML turn on at SR minimum on time, the shoot through between primary side low side FET and SR FET happen. SR FET voltage over stress due to sharp di/dt on leakage inductance. See in [Figure 4-9](#)

Solution:

1. In series a resistor (~2ohm) on AUX rectifier diode path.
2. Change the rectifier diode from Schottky to fast recovery diode.

The purpose of two work-arounds is to increase AUX loop impedance to let more current flow into secondary side to prevent SR minimum on time happen. After that, the user have to check at low output voltage no load operation, whether the controller running at survival mode when. Trade-off maybe need to be made between this issue happens and running at survival mode.

4.3.3 SR MOSFET Vds Voltage Overstress Due to PWMH Partial Turn On At Load Transition

This could be caused by not correctly selected the isolator driver. When power stage running at no load, long burst off time will let isolator VCC drop to lower than UVLO. Once heavy load happens on output, controller will transfer to AAM mode, and PWMH enabled, but isolator driver cannot immediately response the PWMH due to the long power on delay of isolator (typical power on delay time of ISO7710F is 31us), after power on delay time terminated, isolator will respond to PWMH immediately, then partial turn on maybe randomly happens since ISO7710 is a *level-based* driver, As illustrated in [Figure 4-12](#) short PWMH turn on time results in Non-ZCS turn off of SR FET, lead to VDS overstress. As shown in [Figure 4-10](#) and [Figure 4-11](#).

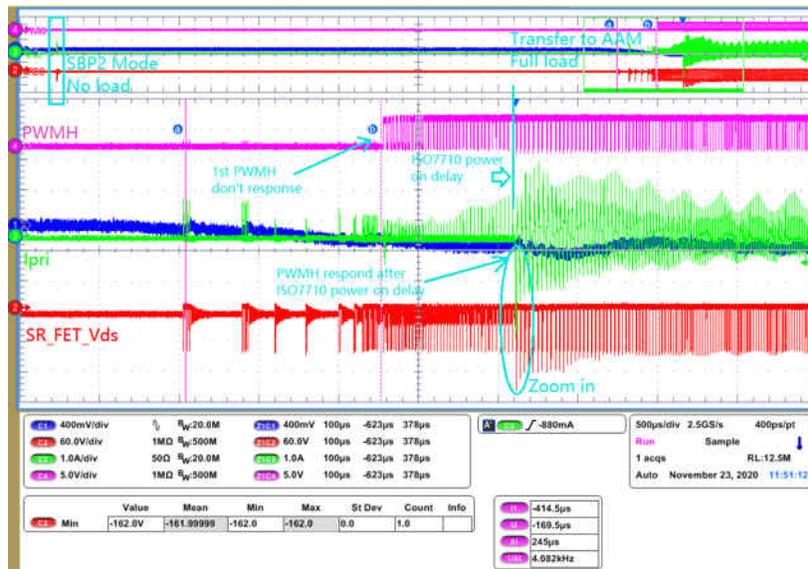


Figure 4-10. PWMH Partial Turn On

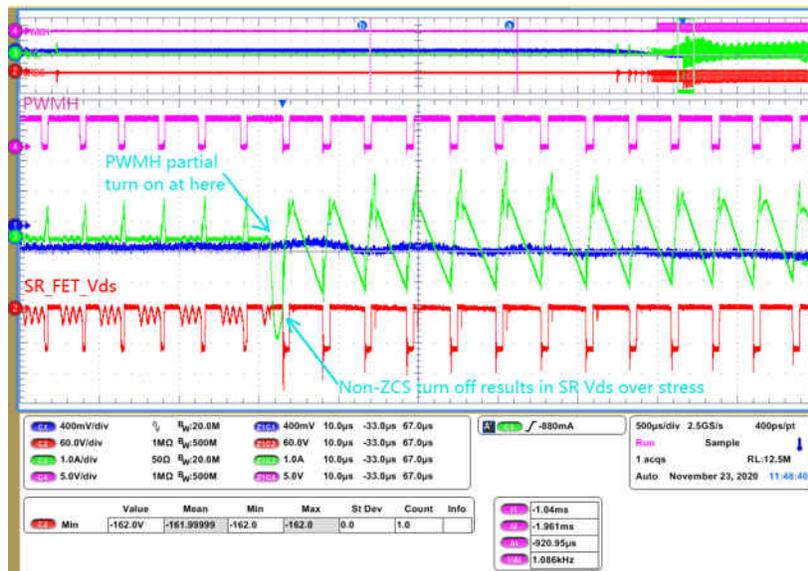


Figure 4-11. PWMH Partial Turn On – Zoom In

Solution:

Change isolator driver from *level-based* driver to *edge-based* driver [Figure 4-13](#), such as ISO7310, it can prevent partial response to PWMH. Then SR is able to ZCS turn off to avoiding over stress. After change to ISO7310, The waveforms shown in [Figure 4-14](#).

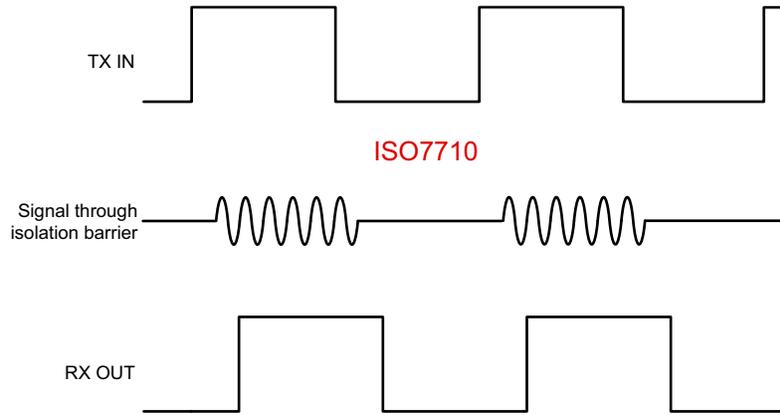


Figure 4-12. Level Based Isolation Driver Architecture

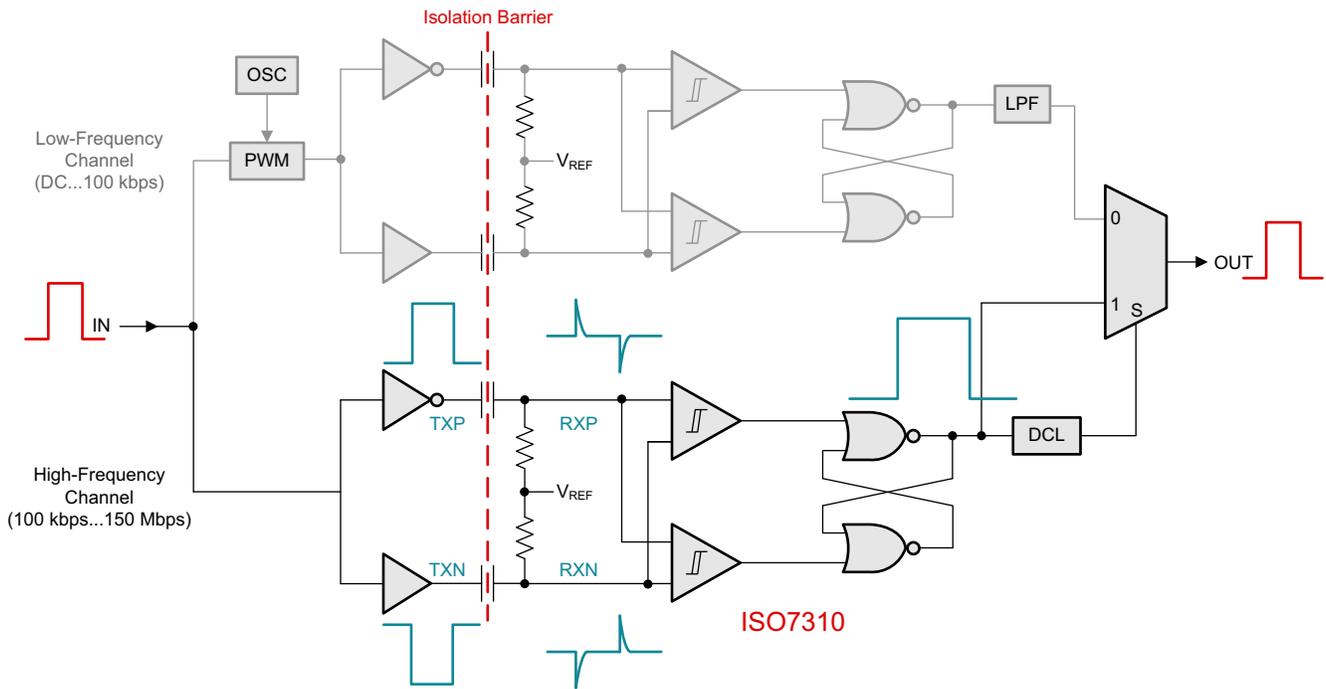


Figure 4-13. Edge Based Isolation Driver Architecture

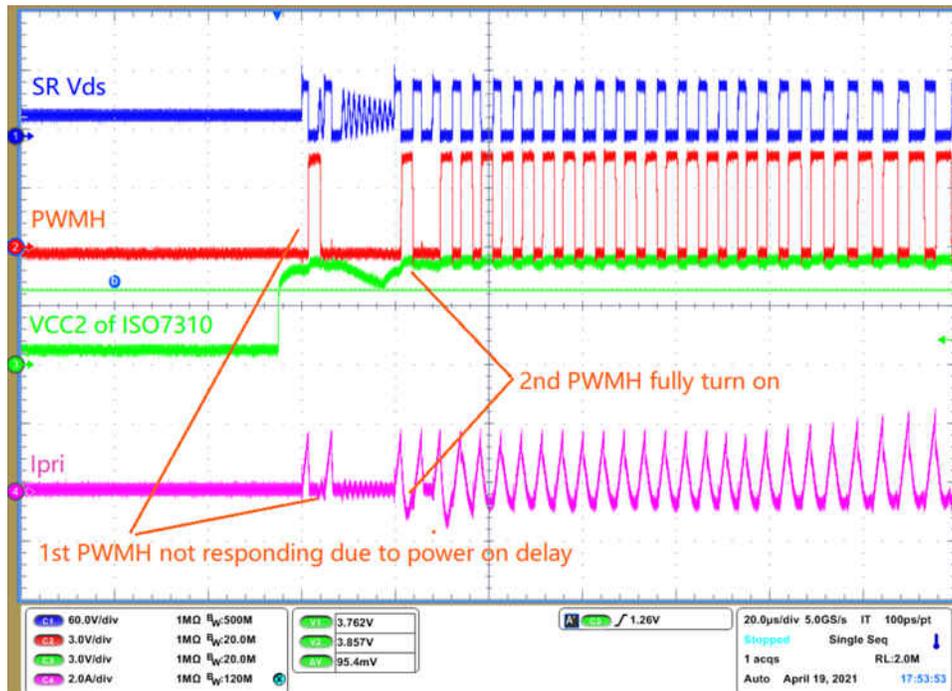


Figure 4-14. Isolator Change to ISO7310

5 References

1. Texas Instruments, [UCC28782 High Density Active Clamp Flyback Controller with EMI Dithering, X-Cap Discharge, and Bias Power Management](#) data sheet.
2. Texas Instruments, [Debugging UCC28780 ACF Converter Start-up Issues](#) application note.
3. Texas Instruments, [Using the UCC28782EVM-030 65-W USB-C PD High-Density Active-Clamp Flyback Converter](#) user guide.

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